SIMBOL-X

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- science background
- mission
- telescope
- detector payload
- low energy detector

C CS REP

science background

science targets

- \triangleright black holes astrophysics
 - matter in the vicinity of a BH
 - history of supermassive BH formation
- \triangleright particle acceleration in the universe
 - mechanism, efficiency, maximum energy

requirements

\triangleright	energy range	0.5 80 keV	
		(100 keV)	
\triangleright	sensitivity	0.1 10 µCrab	
\triangleright	focal length	18 20 m	
\triangleright	field of view	12 arcmin @ 30 keV	
\triangleright	angular resolution	20 arcsec HEW @ 30	
\triangleright	spectral resolution	150 eV @ 6 keV (Fe	
		1.3 keV @ 68 keV (1	
\triangleright	timing accuracy	~ 100 µsec	

cover the sensitivity gap

▷ SIMBOL-X =





mission

mission scenario

- \triangleright detector and mirror spacecraft
- ▷ 4 days orbit (20.000 / 180.000 km)
- \triangleright > 70 % observation time
- \triangleright time budget
 - 0.5 y commissioning
 - 2.5 y nominal operational phase
 - 2 y extension provision
- \triangleright net science time: > 100 Msec
- \triangleright no. of pointings: ~ 1000 (+ 500)
- \triangleright on-board data storage
- \triangleright telemetry 1x / orbit

status

- French-Italian-German consortium
- ▷ phase A (F, D → Jun07, I → Nov07)
- \triangleright phase B likely to come in 2008
- ▷ launch end 2013 (Soyuz/Kourou)



formation flight

- \triangleright probably 1st science mission
- \triangleright autonomous operation
- alignment by radio antennas and laser system
- \triangleright positioning accuracy: 1 x 1 x 3 cm³
- ▷ positioning knowledge: 0.5 x 0.5 cm²



telescope

leadership

- ▷ Osservatorio Astronomico di Brera, Italy
- ▷ industry contract: Alenia

principle

 \triangleright nested mirrors, Wolter-I geometry

technique

- ▷ Ni electroforming replication
- ▷ Pt/C multi-layer coating by sputtering
- \triangleright 2 spider support structures

parameters

\triangleright	no.	of she	lls	~ 100
	_			

- \triangleright focal length 20 m
- \triangleright diameter ~ 70 cm
- \triangleright shell tickness 1/3 of XMM



- effective area (on axis)
 - ▷ > 1000 cm2 @ 2 keV
 - ▷ > 600 cm2 @ 8 keV
 - ▷ > 100 cm2 @ 70 keV



detector payload



CONCEPTION OF

detector payload

- Iow energy detector (LED)
 - \triangleright energy range 0.5 ... 20 keV
- high energy detector (HED)
 - \triangleright energy range 5 keV ...
 - CdTe / CdZnTe (both under test)
 - Derta pixel size 625 x 625 μm
 - \triangleright focal plane format 128 x 128
 - \triangleright sub-units of 16 x 16
 - \triangleright 3D integration of fe-electronics
 - \triangleright status: working 8 x 8 module
- active anti-coincidence shield
 - \triangleright plastic scintillator
 - \triangleright PMT readout
 - \triangleright fibre coupling
 - ▷ status: material selection





"Calliste64" HED subunit

- → Calliste256
- 1 cm²
- 4 side buttable
- 4 r/o ASICs
- self-triggered
- 64 x in FP

LED requirements

- science drivers
 - cosmic X-ray
 background
 estimation
 - \triangleright source confusion limit

- source identification, overlap with HED
- \triangleright Fe line spectroscopy
- > anticoincidence
- \triangleright pulsar timing studies
- \triangleright hard X-ray mission

- specifications
 - field of view
 12 arcmin
 7 cm Ø
 - angular resolution
 20 arcsec point spread function
 1.9 mm
 - energy range
 0.5 ... 20 keV
 - energy resolution 150 keV @ 6 keV
 - \triangleright min. frametime
 - time resolution 100 µsec
 - ▷ "transparent"
 - ▷ s/c constraints

LED parameters

- format
 8 x 8 cm²
 128 x 128 pixels
- pixel size
 625 μm □
- thin entrance window thickness 450 µm
- Iow electronic noise **≤ 10 el. ENC**
- r/o time / row
 4 µsec
- window mode 32 pixels
- \triangleright monolithic device
- high temperature -40 °C

LED layout

- collaboration
 - HLL/MPE: detector, thermal and mechanical interfaces
 - \triangleright IAAT: daq system
- Macro Pixel Detector
 - ▷ SDD & DEPFET
 - \triangleright pixel size 625 µm \Box
 - \triangleright focal plane format 128 x 128
 - ▷ sensitive area 8 x 8 cm²
 - largely redundant quadrants,
 individual r/o & control
- readout modes
 - full frame
 CCD-like, bi-directional
 - \triangleright window mode

selectable window size, no additional hardware



LED dummy

SIMBOL-X LED dummy

- design according to the current state
 of knowledge and technology
- ▷ 128 x 128 pixels (625 µm) organised in 4 independent quadrants
- \triangleright processing of dummy wafers finished
- \triangleright front- and backside metallisation
- \triangleright for demonstration
- \triangleright structural & thermal model (phase B)





LED readout and control

Active Pixel Sensor – XEUS prototype



- CAMEX 64 readout chip (baseline)
 - ▷ 64 channel amplifier
 - ▷ source follower
 - ▷ 8-fold CDS filter
 - ▷ 64/1 analog multiplexer
 - $\,\triangleright\,$ readout time / row \sim 6 μsec

- 2 x SWITCHER-II control ASIC
 - ▷ 64 channel control chip
 - ▷ 2 ports / channel
 - \triangleright supply of switched voltages
 - $\,\triangleright\,$ high voltage CMOS process
 - > 20 V p-p
 - \triangleright 50 MHz clock
- VELA readout chip (option)
 - \triangleright collaboration with PoliMi
 - \triangleright 4 channel prototype tested
 - \triangleright 64 channel version in design
 - ▷ drain current readout
 - \triangleright current integration / deintegration filter
 - \triangleright readout time / row < 3 µsec

LED performance

experience from

- ▷ XEUS WFI 64 x 64 prototypes
 - DEPFET pixels $75 \times 75 \ \mu m^2$
 - readout time / row \sim 20 µsec
 - FWHM @ 6 keV 133 eV
- ▷ Macro Pixel Detector 4 x 4 prototype
 - pixel size 1 x 1 mm²
 - integration time 1 µsec
 - FWHM @ 6 keV 122 eV
- extrapolated SX energy resolution
 - \triangleright assumptions
 - RT leakage current 0.1 ... 1 nA/cm²
 - r/o time / row 4 µsec
 - serial noise 5 el. r.m.s.
 - $Descript{S}$ radiation damage by solar protons
 - real results soon to come





LED demonstrator

quadrant prototype

- science verification module
 phase B, operation with HED
- \triangleright 500 µm \square pixels
- \triangleright format 64 x 64
- ▷ sensitive area 32 x 32 mm²

status

- \triangleright 2 chips on PXD5 production
- ▷ difference in DEPFET clear structure
- \triangleright 1st Al layer, to be patterned this week
- \triangleright available in Jul07





summary & outlook

Low Energy Detector

Simbol-X representative detector in summer

Simbol-X mission

good chance to get into phase B in 2008

... if that occurs

flight hardware processing in 2008